imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832 Email & Skype: info@chipsmall.com Web: www.chipsmall.com Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



LIXYS

HiPerRF[™] Power MOSFETs F-Class: MegaHertz Switching

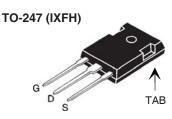
N-Channel Enhancement Mode Avalanche Rated, Low Q_g , Low Intrinsic R_g , High dV/dt, Low t_{rr}

Symbol	Test Conditions	Maximum Ratings			
V _{DSS}	$T_{J} = 25^{\circ}C$ to $150^{\circ}C$	1000	V		
V _{dgr}	$T_{_J}$ = 25°C to 150°C, $R_{_{GS}}$ = 1M Ω	1000	V		
V _{gss} V _{gsm}	Continuous Transient	± 20 ± 30	V V		
I _{D25}	$T_c = 25^{\circ}C$	12	A		
I _{DM}	$\rm T_{_C}$ = 25°C, pulse width limited by $\rm T_{_{JM}}$	48	A		
I _{AR}	$T_c = 25^{\circ}C$	12	A		
E _{AS}	$T_c = 25^{\circ}C$	1	J		
dV/dt	$\begin{split} I_{_{S}} &\leq I_{_{DM}}, \ \text{di/dt} \leq 100 \text{A/} \mu \text{s}, \ V_{_{DD}} \leq V_{_{DSS}} \\ T_{_{J}} \leq 150^{\circ}\text{C}, \ \text{R}_{_{G}} = 2 \Omega \end{split}$	20	V/ns		
P _D	$T_c = 25^{\circ}C$	300	W		
T,		-55 +150	°C		
Т _{јм}		150	°C		
T _{stg}		-55 +150	°C		
T	Maximum lead temperature for soldering	300	°C		
T _{sold}	Plastic body for 10s	260	°C		
M _d	Mounting torque (TO-247)	1.13/10	Nm/lb.in.		
Weight	TO-247 TO-268	6 4	g g		

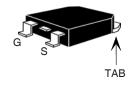
Symbol (Τ _J = 25°C, ι	Test Conditions unless otherwise specified)	Cha Min.	Characteristic Values Min. Typ. Max.			
BV _{DSS}	$V_{gs} = 0V, I_{d} = 1mA$	1000			V	
V _{GS(th)}	$V_{_{DS}} = V_{_{GS}}, I_{_{D}} = 4mA$	3.0		5.5	V	
I _{gss}	$V_{_{GS}} = \pm 20V, V_{_{DS}} = 0V$			± 100	nA	
I _{DSS}	$V_{DS} = V_{DSS}$ $V_{GS} = 0V$ $T_{J} = 125^{\circ}C$			50 1.5	μA mA	
R _{DS(on)}	$V_{GS} = 10V, I_{D} = 0.5 \bullet I_{D25}, \text{ Note } 1$			1.05	Ω	

IXFH12N100F IXFT12N100F

$V_{DSS} = 1000V I_{D25} = 12A R_{DS(on)} ≤ 1.05Ω t_{rr} ≤ 250ns$



TO-268 (IXFT)



Features

- RF capable MOSFETs
- Double metal process for low gate resistance
- Rugged polysilicon gate cell structure
- Unclamped Inductive Switching (UIS) rated
- Low package inductance
- easy to drive and to protect
- Fast intrinsic rectifier

Applications

- DC-DC converters
- Switched-mode and resonant-mode power supplies, >500kHz switching
- DC choppers
- 13.5 MHz industrial applications
- Pulse generation
- Laser drivers
- RF amplifiers

Advantages

- Space savings
- High power density

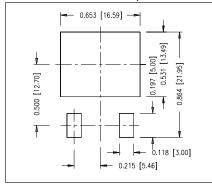
IXFH12N100F IXFT12N100F

Symbol (T ₁ = 25°0	Test Conditions C unless otherwise specified)	Characteristic Values Min. Typ. Max.			
g _{fs}	$V_{DS} = 10V, I_{D} = 0.5 \bullet I_{D25}, Note 1$	8	12	S	
C _{iss})		2700	pF	
C _{oss}	$V_{GS} = 0V, V_{DS} = 25V, f = 1MHz$		305	pF	
C _{rss}	J		93	pF	
t _{d(on)}			12	ns	
t,	Resistive Switching Times $V_{GS} = 10V, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 0.5 \cdot I_{D25}$		9.8	ns	
t _{d(off)}	$\begin{cases} v_{GS} = 10^{\circ}, v_{DS} = 0.3^{\circ}, v_{DSS}, v_{D} = 0.3^{\circ}, v_{D25} \\ R_{c} = 2\Omega \text{ (External)} \end{cases}$		31	ns	
t,	$\int \Pi_{G} = 232$ (External)		12	ns	
Q _{g(on)})		77	nC	
Q _{gs}	$V_{GS} = 10V, V_{DS} = 0.5 \cdot V_{DSS}, I_{D} = 0.5 \cdot I_{D25}$		16	nC	
Q _{gd}	J		42	nC	
R _{thJC}				0.42 °C/W	
R _{thCS}	(TO-247)		0.21	°C/W	

Source-Dr Τ _J = 25°C ι	ain Diode (Inless otherwise specified) Mi		racteristic Values Typ. Max.				
I _s	V _{GS} = 0V		12	Α			
I _{SM}	Repetitive, pulse width limited by $\mathrm{T}_{_{\mathrm{JM}}}$		48	Α			
V _{SD}	$I_F = I_S, V_{GS} = 0V$, Note 1		1.5	V			
t _{rr}	$I_{F} = 12A$, -di/dt = 100A/µs		250	ns			
Q _{RM}	$V_{R} = 100V, V_{GS} = 0V$	0.8		μC			
I _{RM} J	n Go	7.0		А			

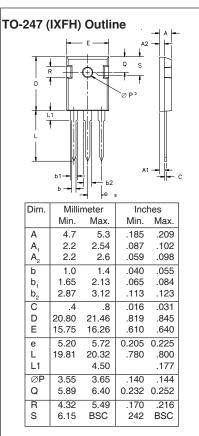
Note: 1. Pulse test, t \leq 300 μ s, duty cycle d \leq 2 %

Min Recommended Footprint



IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions

intro receives the high to ondrige Limits, rest conditions, and Dimensions.										
IXYS MOSFETs and IGBTs are covered	4,835,592	4,931,844	5,049,961	5,237,481	6,162,665	6,404,065 B1	6,683,344	6,727,585	7,005,734 B2	7,157,338B2
by one or more of the following U.S. patents:	4,850,072	5,017,508	5,063,307	5,381,025	6,259,123 B1	6,534,343	6,710,405 B2	6,759,692	7,063,975 B2	
	4,881,106	5,034,796	5,187,117	5,486,715	6,306,728 B1	6,583,505	6,710,463	6,771,478 B2	7,071,537	



TO-268 Outline

